## **MECHANICAL CASE OUTLINE** PACKAGE DIMENSIONS

SCALE 4:1

В

Ρ.

SEATING PLANE

T

**ON Semiconductor** 



US8 **CASE 493** ISSUE D NOTES: -X Y 1. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982 CONTROLLING DIMENSION: MILLIMETERS. 2. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH **DETAIL E** 4. AND PROTRUSION SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203MM (0.003-0.008"). 5. C ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508MM (0.0002"). 6. INCHES MIN MAX MILLIMETERS R DIM MIN MAX G 1.90 0.075 0.083 Α 2.10 В 0.087 0.094 2.20 2.40 С 0.60 0.90 0.024 0.035 0.25 0.007 0.010 0.008 0.014 D F 0.17 С - H 0.20 G 0.50 BSC 0.020 BSC 0.10 (0.004) Т  $\square$ κ Н 0.40 REF 0.016 REF N→ J 0.10 0.18 0.004 0.007 R 0.10 TYP 0.000  $\oplus$ 0.10 (0.004) 🕅 Т Х Y κ 0.00 0.10 0.004 3.00 0.118 0.128 3.20 М 0 6 0 6 N P 0 10 0 10 м 0.010 0.23 0.34 0.013 R 0.23 0.33 0.009 0.013 S 0.37 0.47 0.015 0.019 Ŭ 1 0.80 0.60 0.024 0.031 F ٧ 0.12 BSC 0.005 BSC DETAIL E GENERIC **MARKING DIAGRAM\*** RECOMMENDED **SOLDERING FOOTPRINT\*** ABF 0.30 XX M= <sup>8X</sup> 0.68 3.40 = Specific Device Code XX Μ = Date Code

= Pb-Free Package

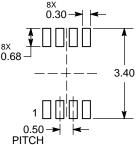
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(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking.

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DESCRIPTION:	US8	PAGE 1 OF 2	

## DATE 15 JUL 2015



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ BY R. FORNESS	19 MAR 2001
А	CHANGED DIM "P" TO 0.23 MM MIN, 0.34 MM MAX AND 0.010 IN MIN, 0.013 IN MAX. REQ BY J. MILLER	25 JUN 2003
В	ADDED SOLDERING FOOTPRINT. REQ. BY D. TRUHITTE.	13 APR 2006
С	MODIFIED SOLDERING FOOTPRINT. REQ. BY B. BECKER.	23 MAR 2015
D	MODIFIED DIMENSION A MIN VALUE AND DIMENSION C MAX VALUE FOR MM. REQ. BY R. AVILA.	15 JUL 2015

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